

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	You-Wei Lin	10/08/2020
	Chih-Feng Fan	10/08/2020
RECEIVING PARTY DATA		
Name:	MEDIATEK INC.	
Street Address:	No. 1, Dusing Rd. 1st, Science-Based Industrial Park	
City:	Hsin-Chu	
State/Country:	TAIWAN	
PROPERTY NUMBERS Total: 1		
	Property Type	Number
	Application Number:	17070885
CORRESPONDENCE DATA		
Fax Number:		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	3027291562	
Email:	Patent.admin.uspto.cr@naipo.com	
Correspondent Name:	WINSTON HSU	
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Address Line 4:	NEW TAIPEI CITY, TAIWAN	
ATTORNEY DOCKET NUMBER:	MTKP3569USA	
NAME OF SUBMITTER:	SIBYL YU	
SIGNATURE:	/SIBYL YU/	
DATE SIGNED:	10/14/2020	
Total Attachments: 4		
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Docket No MTKP3569USA

**COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION
USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT**

Title of Invention:

SEMICONDUCTOR PACKAGE AND FABRICATION METHOD THEREOF

As the below named inventor, I hereby declare that:
This declaration is directed to:

- ☒ The attached application, or
- ☐ United States application number _____ filed on _____, or
- ☐ PCT international application number _____ filed on _____

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

In consideration of the payment by MEDIATEK INC. having a postal address of

No. 1, Dusing Rd. 1st, Science-Based Industrial Park, Hsin-Chu 300, Taiwan, R.O.C.

(referred to as "ASSIGNEE" below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.

I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;

I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal

representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the purposes thereof.
IN WITNESS WHEREOF, I have hereunto set hand and seal this on the date(s) indicated.

Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.

Docket No MTKP3569USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **You-Wei Lin**

Date: 2020, Oct-8

Signature:

You-Wei Lin

Docket No MTKP3569USA

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Docket No MTKP3569USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: **Chih-Feng Fan**

Date: 2020 Oct. 8

Signature: Chih-Feng Fan

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CUST#MTKL-20-0386US

Page 4 of 4

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